1. Package summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>package length</td>
<td>1.8</td>
<td>-</td>
<td>2</td>
<td>2.2</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
<td>1.15</td>
<td>-</td>
<td>1.25</td>
<td>1.35</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
<td>0.8</td>
<td>-</td>
<td>0.95</td>
<td>1.1</td>
<td>mm</td>
</tr>
<tr>
<td>nominal pitch</td>
<td>-</td>
<td>-</td>
<td>0.65</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>-</td>
<td>6</td>
<td>-</td>
<td>A/A</td>
</tr>
</tbody>
</table>

Table 1. Package summary
2. Package outline

Plastic surface-mounted package; 6 leads

<table>
<thead>
<tr>
<th>UNIT</th>
<th>A</th>
<th>A1 max</th>
<th>b_p</th>
<th>c</th>
<th>D</th>
<th>E</th>
<th>e</th>
<th>e1</th>
<th>H_E</th>
<th>L_p</th>
<th>Q</th>
<th>v</th>
<th>w</th>
<th>y</th>
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</thead>
<tbody>
<tr>
<td>mm</td>
<td>1.1</td>
<td>0.1</td>
<td>0.30</td>
<td>0.25</td>
<td>2.2</td>
<td>1.35</td>
<td>1.3</td>
<td>0.65</td>
<td>2.2</td>
<td>2.0</td>
<td>0.45</td>
<td>0.25</td>
<td>0.2</td>
<td>0.1</td>
</tr>
</tbody>
</table>

DIMENSIONS (mm are the original dimensions)

Fig. 1. Package outline TSSOP6 (SOT363)
3. Soldering

Fig. 2. Reflow soldering footprint for TSSOP6 (SOT363)

Fig. 3. Wave soldering footprint for TSSOP6 (SOT363)
4. Legal information

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SOT363

plastic, surface-mounted package; 6 leads; 0.65 mm pitch; 2 mm x 1.25 mm x 0.95 mm body

5. Contents

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